## **DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL**

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor** within 30 days of receipt of this notification.

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

<u>Technical Contact:</u> Name: Rivero, Douglas E-mail: Doug.Rivero@fairchildsemi.com Phone: 1-408-822-2143

<u>PCN Originator:</u> Name: Kalabkova, Ivana E-mail: Ivana.Kalabkova@notes.fairchildsemi.com Phone: 408-822-2187

Implementation of change: Expected 1st Device Shipment Date: 2008/03/02

Earliest Year/Work Week of Changed Product: 0810

Change Type Description: Die Revision

Description of Change (From): Current die size: 76x38

Description of Change (To): New die size: 83x40

Reason for Change : The mask set for this device was modified to improve the Rg performance of the part from a typical of 9 Ohms to 4.5 Ohms.

Qual/REL Plan Numbers : Q20050144

Qualification :

All qualification tests passed the defined qualification plan requirement.

## **Results/Discussion**

Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20050144AAHTRB	FDS6681Z	0/79			
			0/79		
				0/79	
Q20050144ABHTRB		0/79			
			0/79		
				0/79	
Test: 130C (Highly	Accelerated Stres	ss Test)			
Lot	Device	Device		F	ailure Code
Q20050144AAHAST1	FDS66817	FDS6681Z			

Q20050144ABHAST1	FDS6681Z	0/79					
Test: MSL(1), PKG(Small), PeakTemp(260c), Cycles(3) (Precondition)							
Lot	Device	Results	Failure Code				
Q20050144AAPCNL1A	FDS6681Z	0/79					
Q20050144ABPCNL1A	FDS6681Z	0/79					

Product Id Description : Fairchild Semiconductor's selected products in the NMSON package. Products affected by this change are listed below in the "Affected FSIDs" section.

Affected FSIDs :

FDS4935BZ	FDS4935BZ_SBME002	